



DXTP03100CFG

#### 100V PNP LOW VCESAT TRANSISTOR IN PowerDI3333-8

#### Features

- BV<sub>CEO</sub> > -100V
- Small Form Factor Thermally Efficient Package.
   Enables Higher Density End Products
- I<sub>C</sub> = -5A Continuous Collector Current
- I<sub>CM</sub> = -10A Peak Pulse Current
- Low Saturation Voltage V<sub>CE(sat)</sub> < -100mV @ -1A</li>
- R<sub>SAT</sub> = 60mΩ for a Low equivalent On-Resistance
- hFE Specified up to -10A for a High Gain Hold-Up
- Complementary NPN Type: DXTN03100CFG
- Rated to +175°C Ideal For High Temperature Environment
- Wettable Flank For Improved Optical Inspection
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

## **Mechanical Data**

- Case: PowerDI<sup>®</sup>3333-8
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads Solderable per MIL-STD-202, Method 208 <sup>(3)</sup>
- Weight: 0.03 grams (Approximate)

#### Applications

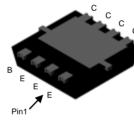
- Motor Driving
- Line Switching
- High Side Switches

PowerDI3333-8 (SWP) (Type UX)

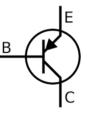
Equivalent Circuit



Top View



Bottom View



**Device Symbol** 

#### Ordering Information (Note 4)

Part Number	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DXTP03100CFG-7	2K1	7	12	2,000
Notes: 1 No purposely added lead. Fully FLI Directive 2002/95/FC (RoHS): 2011/65/FLI (RoHS 2) & 2015/863/FLI (RoHS 3) compliant				

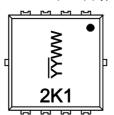
 See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

#### **Marking Information**

PowerDI3333-8 (SWP) (Type UX)



2K1= Product Type Marking Code  $\overline{YY}WW$  = Date Code Marking  $\overline{YY}$  = Last Two Digits of Year (ex: 19 = 2019) WW = Week Code (01 to 53)

PowerDI is a registered trademark of Diodes Incorporated. DXTP03100CFG Datasheet Number: DS41058 Rev. 1 - 2

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# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-110	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-100	V
Emitter-Base Voltage	V <sub>EBO</sub>	-7	V
Continuous Collector Current	lc	-5	A
Peak Pulse Current	ICM	-10	A

## Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
	(Note 5)		1.07	W
Power Dissipation	(Note 6)	PD	2.3	W
	(Note 7)		3.4	W
	(Note 5)		140	°C/W
Thermal Resistance, Junction to Ambient	(Note 6)	R <sub>0JA</sub>	65	°C/W
	(Note 7)		44	°C/W
Thermal Resistance, Junction to Leads (Note 8	R <sub>θJL</sub>	6	°C/W	
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +175	°C	

### ESD Ratings (Note 9)

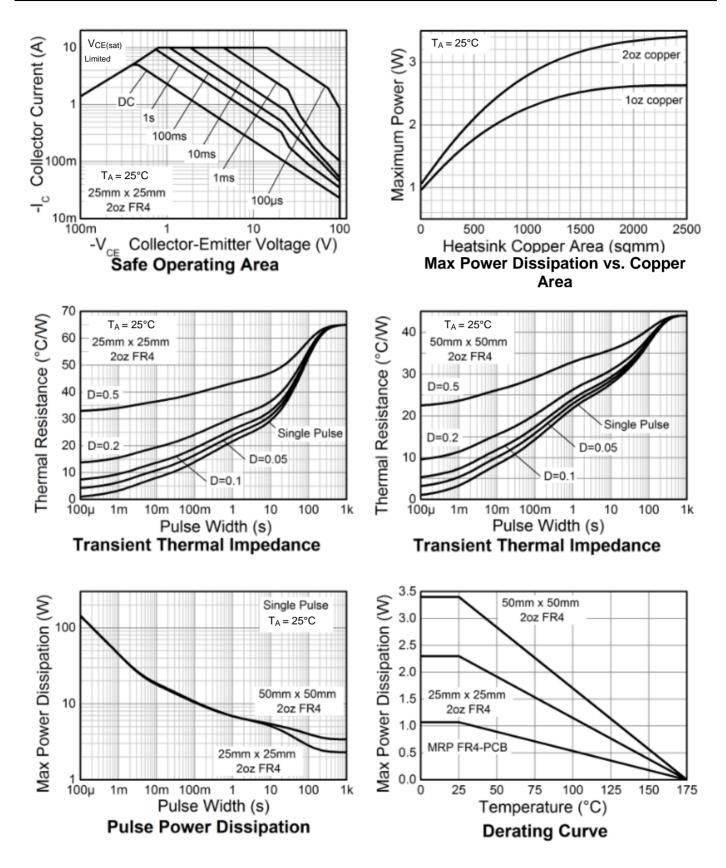
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	ЗA
Electrostatic Discharge - Machine Model	ESD MM	≥ 400	V	С
Notes: 5. For a device mounted with the collector tab on MRP FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.				

5. For a device mounted with the collector tab on MRP FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.

For a device mounted with the collector tab on MRP FR-4 PCS; device is meas
 Same as Note 5, except the device is mounted on 25mm x 25mm 2oz copper.
 Same as Note 5, except the device is mounted on 50mm x 50mm 2oz copper.
 Thermal resistance from junction to solder-point (at the collector tab).
 Refer to JEDEC specification JESD22-A114 and JESD22-A115.



## **Thermal Characteristics and Derating Information**





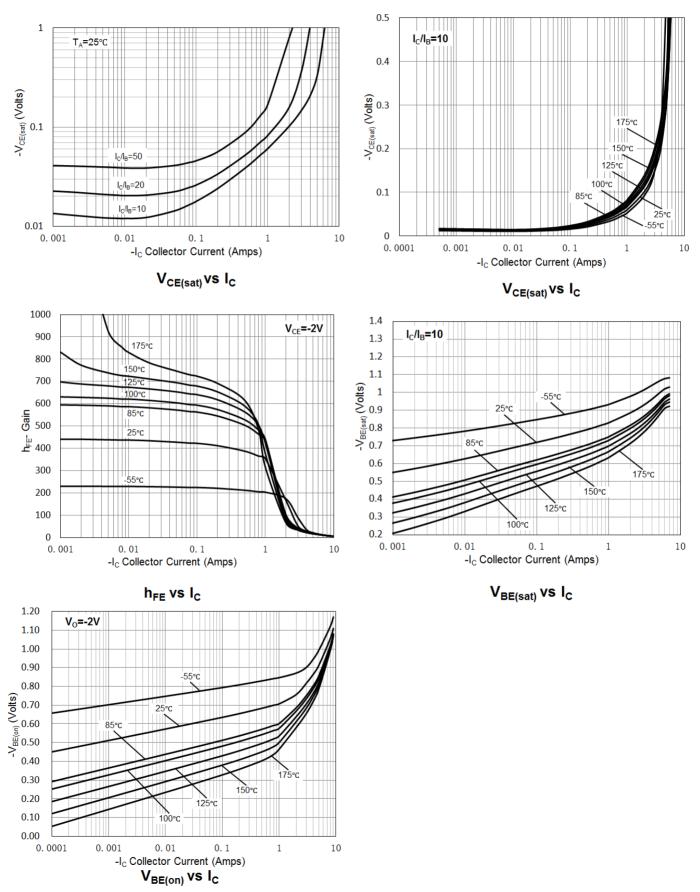
## **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	-110	-138		V	I <sub>C</sub> = -100μA
Collector-Emitter Breakdown Voltage (Note 10)	BV <sub>CEO</sub>	-100	-116		V	I <sub>C</sub> = -10mA
Emitter-Base Breakdown Voltage	BVEBO	-7	-8.8		V	I <sub>E</sub> = -100μA
Collector-Base Cut-Off Current	I <sub>CBO</sub>	_	-1	-50	nA	V <sub>CB</sub> = -100V
Collector-Base Cut-Off Current		_	-0.07	10	μA	V <sub>CB</sub> = -100V, T <sub>A</sub> = +125°C
Collector-Emitter Cut-Off Current ( $R \le 1k\Omega$ )		_	-2	-50	nA	V <sub>CB</sub> = -100V
Collector-Emitter Cut-On Current ( $R \leq 1K\Omega$ )	I <sub>CER</sub>	—	-2.3	50	μA	V <sub>CB</sub> = -100V, T <sub>A</sub> = +125°C
Emitter Cut-Off Current	I <sub>EBO</sub>	—	-1	-20	nA	$V_{EB} = -6V$
		250	421	_	_	$I_{C} = -10 \text{mA}, V_{CE} = -2 \text{V}$
		200	338	800	—	I <sub>C</sub> = -1A, V <sub>CE</sub> = -2V
Static Forward Current Transfer Ratio (Note 10)	L.	180	323	_	—	I <sub>C</sub> = -1.2A, V <sub>CE</sub> = -2V
Static Forward Current Transfer Ratio (Note To)	h <sub>FE</sub>	150	295	-	_	I <sub>C</sub> = -1.5A, V <sub>CE</sub> = -2V
		35	57	—	—	$I_{C} = -3A, V_{CE} = -2V$
		20	29	_	—	$I_{C} = -4A, V_{CE} = -2V$
	V <sub>CE(sat)</sub>	—	-17.5	-40	mV	I <sub>C</sub> = -100mA, I <sub>B</sub> = -10mA
Collector-Emitter Saturation Voltage (Note 10)		—	-60	-100	mV	I <sub>C</sub> = -1A, I <sub>B</sub> = -100mA
		—	-102	-180	mV	$I_{\rm C} = -2A, I_{\rm B} = -200 {\rm mA}$
		—	-212	-380	mV	$I_{C} = -4A, I_{B} = -400 \text{mA}$
Base-Emitter Saturation Voltage (Note 10)	V <sub>BE(sat)</sub>	—	-963	-1.1	mV	$I_{\rm C} = -4A, I_{\rm B} = -400 {\rm mV}$
Base-Emitter Turn-On Voltage (Note 10)	V <sub>BE(on)</sub>	—	-888	-1	mV	$I_{C} = -4A, V_{CE} = -2V$
Output Capacitance	Cobo	—	42	_	pF	$V_{CB} = -10V. f = 1MHz$
Transition Frequency	f⊤	_	125	—	MHz	$V_{CE} = -10V$ , $I_C = -100mA$ f = 50MHz
	t <sub>delay</sub>	—	6.8	—	ns	
Switching Characteristics	t <sub>rise</sub>	_	259	_	ns	$V_{CC} = -10V, I_{C} = -1A$
Switching Characteristics	t <sub>storage</sub>	—	1718	—	ns	$I_{B1} = -I_{B2} = -100 \text{mA}$
	t <sub>fall</sub>	_	185		ns	

Note: 10. Measured under pulsed conditions. Pulse width  $\leqslant$  300µs. Duty cycle  $\leqslant$  2%.



### Typical Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)



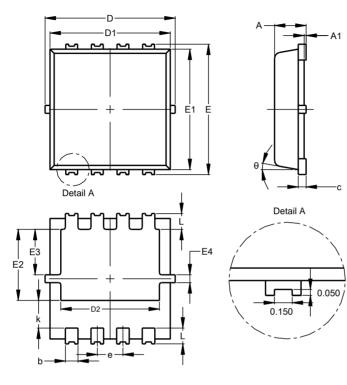
DXTP03100CFG Datasheet Number: DS41058 Rev. 1 - 2



## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI3333-8 (SWP) (Type UX)

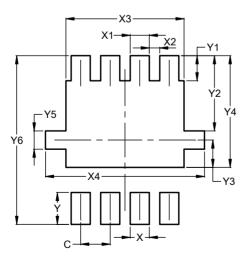


PowerDI3333-8 (SWP)					
	(Type UX)				
Dim	Min Max Typ				
Α	0.75	0.85	0.80		
A1	0.00	0.05			
b	0.25	0.40	0.32		
C	0.10	0.25	0.15		
D	3.20	3.40	3.30		
D1	2.95	3.15	3.05		
D2	2.30	2.70	2.50		
Е	3.20	3.40	3.30		
E1	2.95	3.15	3.05		
E2	1.60	2.00	1.80		
E3	0.95	1.35	1.15		
E4	0.10	0.30	0.20		
е			0.65		
k	0.50	0.90	0.70		
L	0.30	0.50	0.40		
θ	0°	12°	10°		
All Dimensions in mm					

### **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI3333-8 (SWP) (Type UX)



Dimensions	Value (in mm)
С	0.650
Х	0.420
X1	0.420
X2	0.230
X3	2.600
X4	3.500
Y	0.700
Y1	0.550
Y2	1.650
Y3	0.600
Y4	2.450
Y5	0.400
Y6	3.700

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.



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